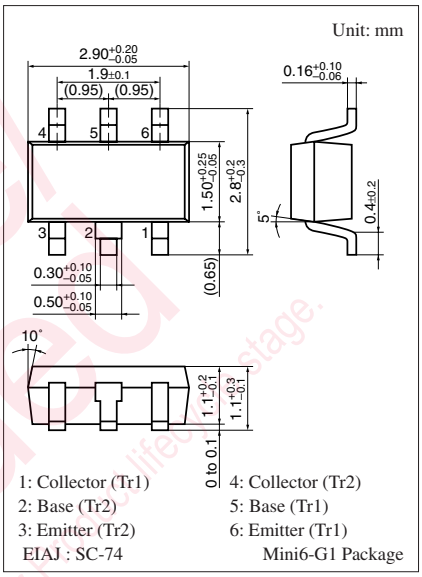
XN04130 (XN4130)

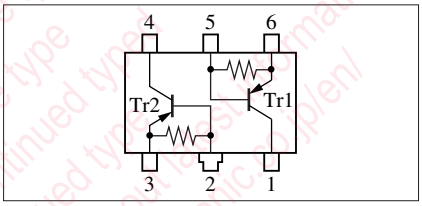
Silicon PNP epitaxial planar type

For amplification of low-frequency output



Marking Symbol: OF

Internal Connection



■ Features

- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- UNR1130 (UN1130) × 2

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−15	V
Collector-emitter voltage (Base open)	V_{CEO}	−15	V
Emitter-base voltage (Collector open)	V_{EBO}	−7	V
Collector current	I_C	− 0.5	A
Peak collector current	I_{CP}	−1	A
Total power dissipation	P_T	300	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

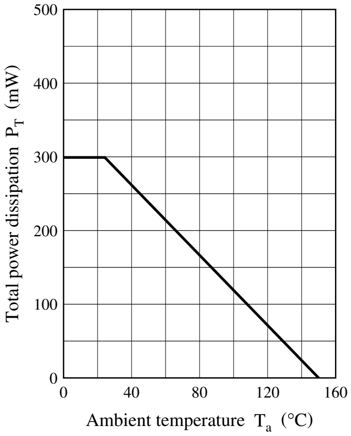
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10$ µA, $I_E = 0$	−15			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -1$ mA, $I_B = 0$	−15			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -1$ mA, $I_C = 0$	−7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10$ V, $I_E = 0$			− 0.1	µA
Forward current transfer ratio *	h_{FE1}	$V_{CE} = -2$ V, $I_C = -500$ mA	80		280	—
	h_{FE2}	$V_{CE} = -2$ V, $I_C = -1$ A	50			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -300$ mA, $I_B = -6$ mA		− 0.2	− 0.3	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = -300$ mA, $I_B = -6$ mA		− 0.9	−1.3	V
Transition frequency	f_T	$V_{CB} = -10$ V, $I_E = 50$ mA, f = 200 MHz		130		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10$ V, $I_E = 0$, f = 1 MHz		22		pF
Base-emitter resistance	R_{BE}		−30%	10	+30%	kΩ

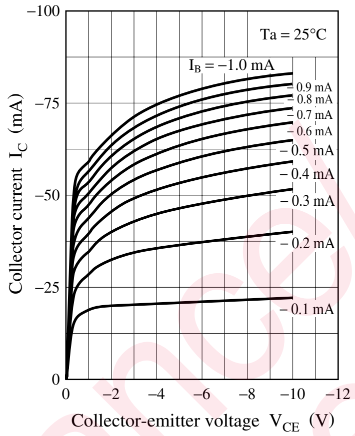
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Pulse measurement

Note) The part number in the parenthesis shows conventional part number.

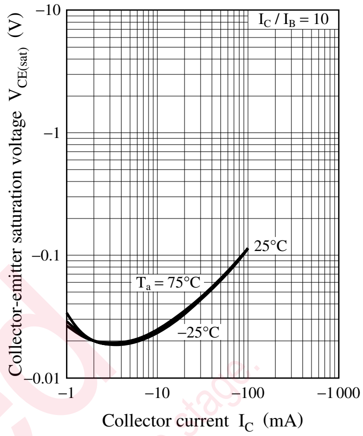
P_T — T_a



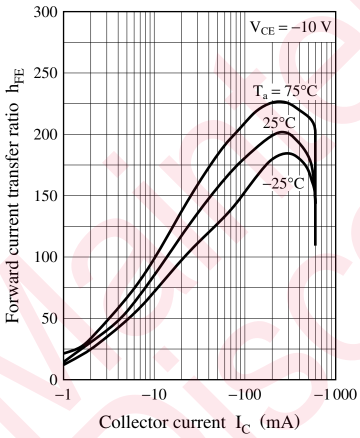
I_C — V_{CE}



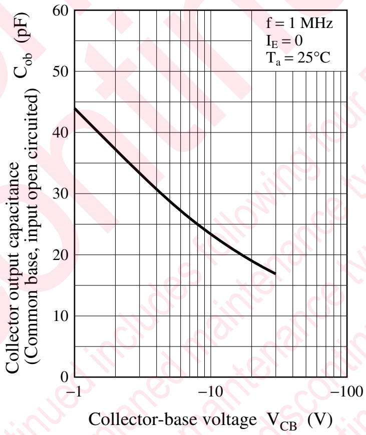
$V_{CE(sat)}$ — I_C



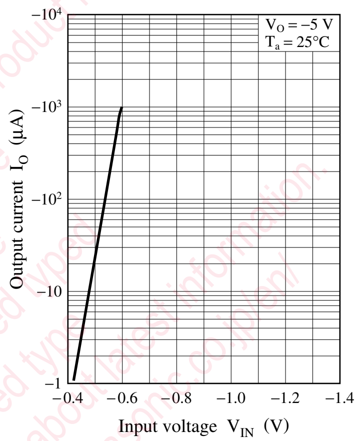
h_{FE} — I_C



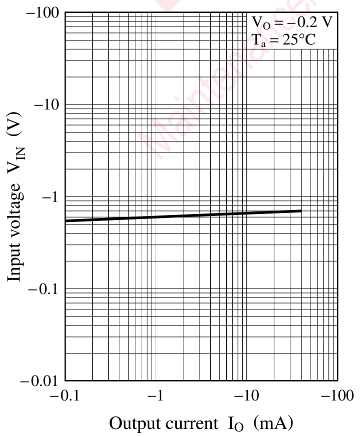
C_{ob} — V_{CB}



I_O — V_{IN}



V_{IN} — I_O



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